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CLAIMS

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1. A process of forming an encapsulated circuit having at least one layer of circuitry, the encapsulated circuit having a first side as an interface side and a second side as a protective cover, characterized in that the process comprises the steps of:

- 10 - applying at least one layer of sequentially processed circuitry on a first side of an interface carrier, a second side of the interface carrier being the interface side of the encapsulated circuit,
- joining the last applied sequentially processed circuitry layer to a support carrier by means of an adhesive layer, the support carrier
15 forming the protective cover of the second side of the encapsulated circuit.

2. The process according to claim 1, characterized in that the process further comprises the step of:

- 20 - applying the adhesive layer on top of the last applied sequentially processed circuitry layer.

3. The process according to claim 1, characterized in that the process further comprises the step of:

- 25 - applying the adhesive layer to the support carrier.

4. The process according to any one of claims 1 to 3, characterized in that the application of at least one of the at least one sequentially processed circuitry layer is by means of offset printing technology.

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5. The process according to claim 4, characterized in that a dielectric of at least one of the at least one sequentially processed circuitry layer is acrylate.
- 5 6. The process according to any one of claims 2 or 3, characterized in that the application of the adhesive layer is by means of offset printing technology.
- 10 7. The process according to any one of claims 1 to 6, characterized in that the support carrier is at least a part of a cover housing in which the encapsulated circuit is mounted.
- 15 8. The process according to any one of claims 1 to 6, characterized in that the support carrier is at least a part of an enclosure on which the encapsulated circuit is mounted.
- 20 9. The process according to any one of claims 1 to 6, characterized in that the support carrier is rigid.
- 20 10. The process according to any one of claims 1 to 6, characterized in that support carrier is bendable.
- 25 11. The process according to any one of claims 1 to 10, characterized in that at at least one of the at least one sequentially processed layer comprises connection circuitry.
- 30 12. The process according to any one of claims 1 to 11, characterized in that at at least one of the at least one sequentially processed layer comprises at least one passive component.

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13. The process according to any one of claims 1 to 12, characterized in that at least one of the at least one sequentially processed layer comprises at least one active component.
- 5 14. The process according to any one of claims 1 to 13, characterized in that the interface layer comprises at least one via.
15. The process according to claim 13, characterized in that at least one of the at least one via is solid.
- 10 16. The process according to any one of claims 1 to 15, characterized in that the interface layer is bendable.
- 15 17. The process according to any one of claims 1 to 16, characterized in that the interface layer is made of polyimide.
18. A device comprising wireless communication means, characterized in that the device comprises an encapsulated circuit made according any one of claims 1 to 17.
- 20 19. A wireless mobile terminal, characterized in that the terminal comprises an encapsulated circuit made according any one of claims 1 to 17.
- 25 20. An encapsulated circuit having at least one layer of circuitry, the encapsulated circuit having a first side as an interface side and a second side as a protective cover, characterized in that the circuit comprises:
- an interface layer having a first side and a second side, a first side of the interface layer being the interface side of the encapsulated circuit,
 - at least one layer of sequentially processed circuitry on the second side of the interface carrier,
 - 30 - a support carrier forming the protective cover of the second side of the encapsulated circuit,

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- an adhesive layer between a top of the last sequentially processed circuitry layer and the support carrier.

5 21. The circuit according to claim 20, characterized in that at least one of the at least one sequentially processed circuitry layer has been added by means of offset printing technology.

10 22. The circuit according to claim 21, characterized in that a dielectric of at least one of the at least one sequentially processed circuitry layer is acrylate.

15 23. The circuit according to any one of claims 20 to 22, characterized in that the adhesive layer has been added by means of offset printing technology.

24. The circuit according to any one of claims 20 to 22, characterized in that the support carrier is at least a part of a cover housing in which the encapsulated circuit is mounted.

20 25. The circuit according to any one of claims 20 to 22, characterized in that the support carrier is at least a part of an enclosure on which the encapsulated circuit is mounted.

25 26. The circuit according to any one of claims 20 to 22, characterized in that the support carrier is rigid.

27. The circuit according to any one of claims 20 to 22, characterized in that the support carrier is bendable.

30 28. The circuit according to any one of claims 20 to 27, characterized in that at least one of the at least one sequentially processed layer comprises connection circuitry.

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29. The circuit according to any one of claims 20 to 27, characterized in that at at least one of the at least one sequentially processed layer comprises at least one passive component.
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30. The circuit according to any one of claims 20 to 29, characterized in that at at least one of the at least one sequentially processed layer comprises at least one active component.
- 15
31. The circuit according to any one of claims 20 to 30, characterized in that the interface layer comprises at least one via.
32. The circuit according to claim 31, characterized in that at least one of the at least one via is solid.
- 20
33. The circuit according to any one of claims 20 to 32, characterized in that the interface layer is bendable.
- 25
34. The circuit according to any one of claims 20 to 33, characterized in that the interface layer is made of polyimide.
35. A device comprising wireless communication means, characterized in that the device comprises an encapsulated circuit according any one of claims 20 to 34.
36. A wireless mobile terminal, characterized in that the terminal comprises an encapsulated circuit according any one of claims 20 to 34.